
2SB562

Silicon PNP Epitaxial

HITACHI

Application

- Low frequency power amplifier
- Complementary pair with 2SD468

Outline

TO-92MOD



1. Emitter
2. Collector
3. Base

Absolute Maximum Ratings (Ta = 25°C)

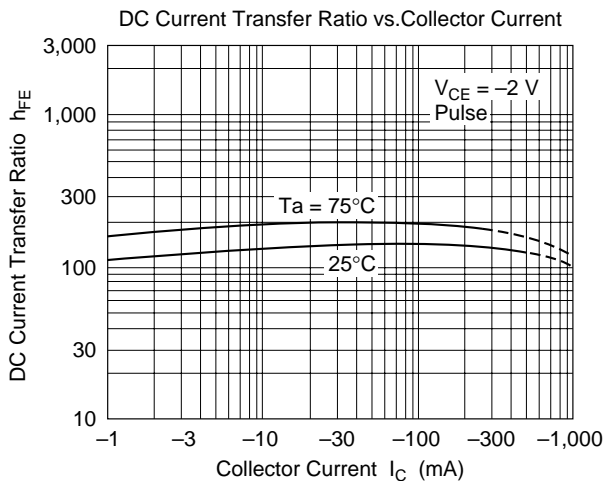
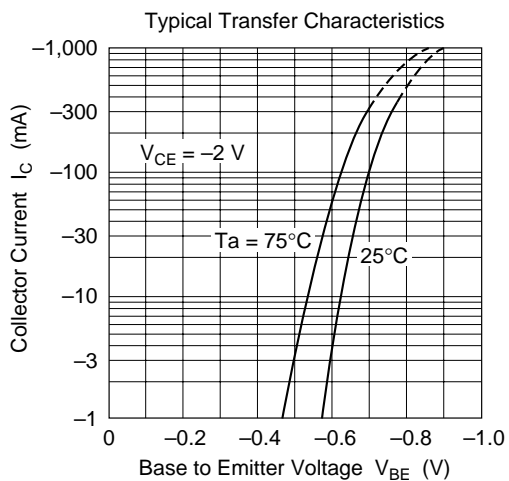
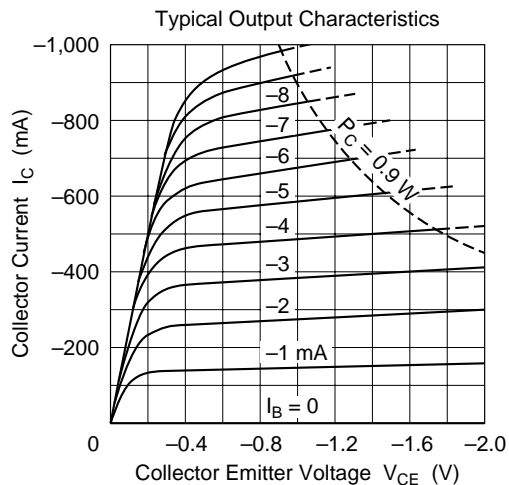
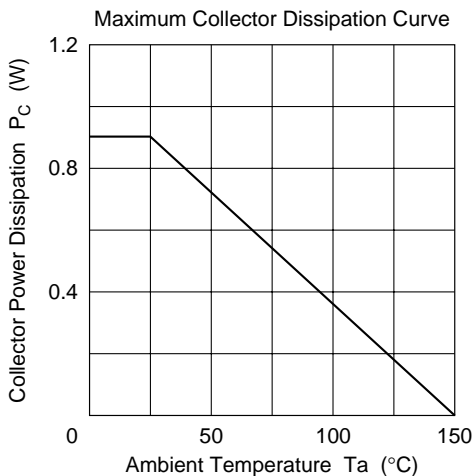
Item	Symbol	Ratings	Unit
Collector to base voltage	V_{CBO}	-25	V
Collector to emitter voltage	V_{CEO}	-20	V
Emitter to base voltage	V_{EBO}	-5	V
Collector current	I_C	-1.0	A
Collector peak current	$i_{C(\text{peak})}$	-1.5	A
Collector power dissipation	P_C	0.9	W
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	-55 to +150	°C

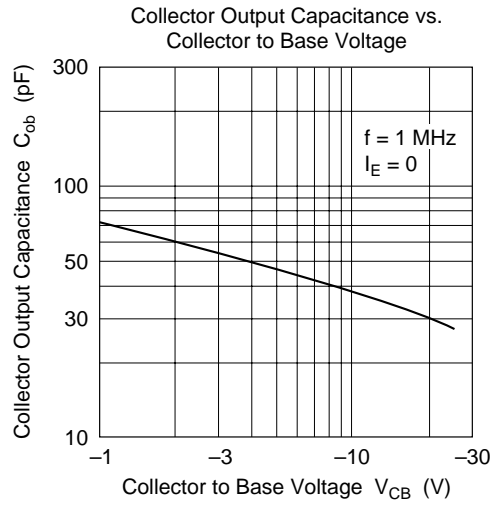
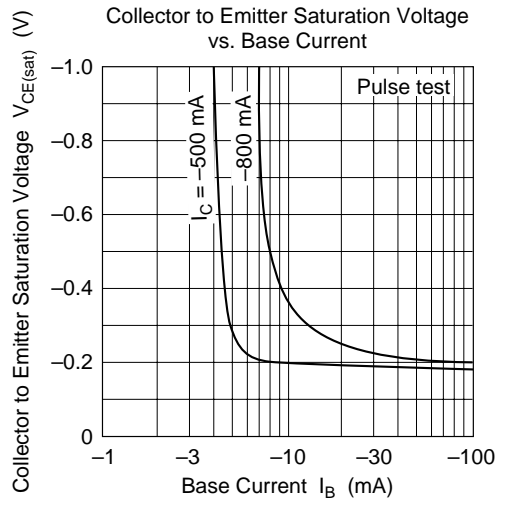
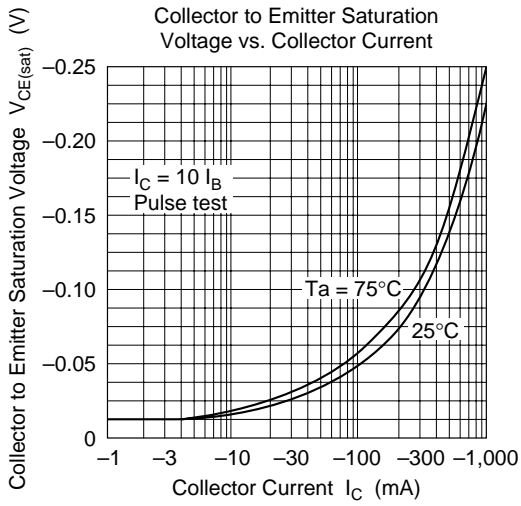
Electrical Characteristics (Ta = 25°C)

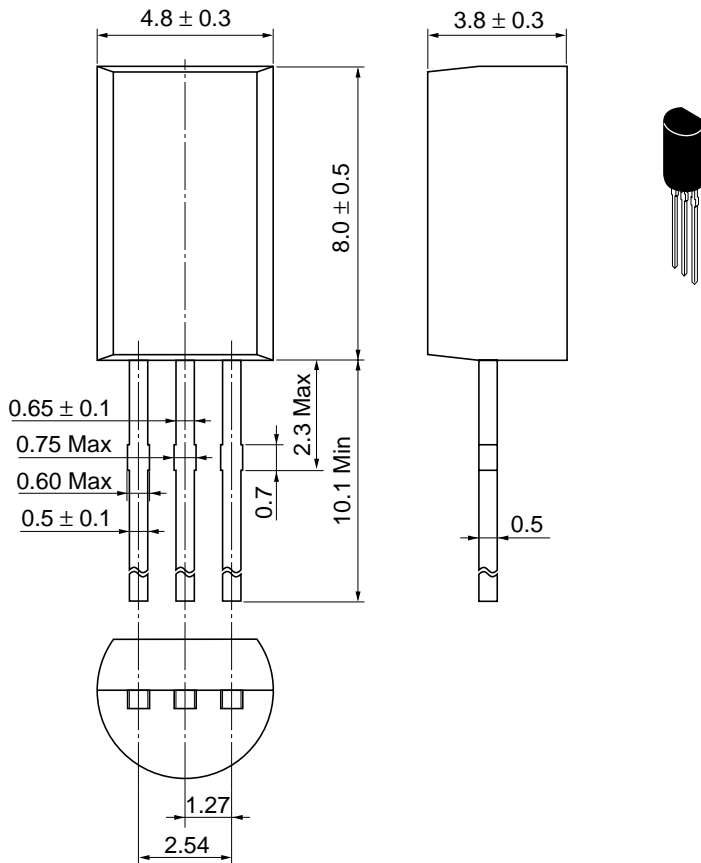
Item	Symbol	Min	Typ	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{(BR)CBO}$	-25	—	—	V	$I_C = -10 \mu\text{A}$, $I_E = 0$
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	-20	—	—	V	$I_C = -1 \text{ mA}$, $R_{BE} = \infty$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	-5	—	—	V	$I_E = -10 \mu\text{A}$, $I_C = 0$
Collector cutoff current	I_{CBO}	—	—	-1.0	μA	$V_{CB} = -20 \text{ V}$, $I_E = 0$
DC current transfer ratio	h_{FE}^{*1}	85	—	240		$V_{CE} = -2 \text{ V}$, $I_C = -0.5 \text{ A}$ (Pulse test)
Collector to emitter saturation voltage	$V_{CE(\text{sat})}$	—	-0.2	-0.5	V	$I_C = -0.8 \text{ A}$, $I_B = -0.08 \text{ A}$ (Pulse test)
Base to emitter voltage	V_{BE}	—	-0.8	-1.0	V	$V_{CE} = -2 \text{ V}$, $I_C = -0.5 \text{ A}$ (Pulse test)
Gain bandwidth product	f_T	—	350	—	MHz	$V_{CE} = -2 \text{ V}$, $I_C = -0.5 \text{ A}$ (Pulse test)
Collector output capacitance	C_{ob}	—	38	—	pF	$V_{CB} = -10 \text{ V}$, $I_E = 0$ $f = 1 \text{ MHz}$

Note: 1. The 2SB562 is grouped by h_{FE} as follows.

B	C
85 to 170	120 to 240







Hitachi Code	TO-92 Mod
JEDEC	—
EIAJ	Conforms
Weight (reference value)	0.35 g

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HITACHI

Hitachi, Ltd.

Semiconductor & Integrated Circuits.
Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan
Tel: Tokyo (03) 3270-2111 Fax: (03) 3270-5109

URL North America : <http://semiconductor.hitachi.com/>
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For further information write to:

Hitachi Semiconductor
(America) Inc.
179 East Tasman Drive,
San Jose, CA 95134
Tel: <1> (408) 433-1990
Fax: <1> (408) 433-0223

Hitachi Europe GmbH
Electronic components Group
Dornacher Straße 3
D-85622 Feldkirchen, Munich
Germany
Tel: <49> (89) 9 9180-0
Fax: <49> (89) 9 29 30 00

Hitachi Europe Ltd.
Electronic Components Group.
Whitebrook Park
Lower Cookham Road
Maidenhead
Berkshire SL6 8YA, United Kingdom
Tel: <44> (1628) 585000
Fax: <44> (1628) 778322

Hitachi Asia Pte. Ltd.
16 Collyer Quay #20-00
Hitachi Tower
Singapore 049318
Tel: 535-2100
Fax: 535-1533

Hitachi Asia Ltd.
Taipei Branch Office
3F, Hung Kuo Building, No.167,
Tun-Hwa North Road, Taipei (105)
Tel: <886> (2) 2718-3666
Fax: <886> (2) 2718-8180

Hitachi Asia (Hong Kong) Ltd.
Group III (Electronic Components)
7/F., North Tower, World Finance Centre,
Harbour City, Canton Road, Tsim Sha Tsui,
Kowloon, Hong Kong
Tel: <852> (2) 735 9218
Fax: <852> (2) 730 0281
Telex: 40815 HITEC HX

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